



Dear customer

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Therefore, all references to "LAPIS Technology Co., Ltd.", "LAPIS Technology"  
and/or "LAPIS" in this document shall be replaced with "ROHM Co., Ltd."

Furthermore, there are no changes to the documents relating to our products other than  
the company name, the company trademark, logo, etc.

Thank you for your understanding.

ROHM Co., Ltd.  
April 1, 2024

Dear customer

LAPIS Semiconductor Co., Ltd. ("LAPIS Semiconductor"), on the 1<sup>st</sup> day of October, 2020, implemented the incorporation-type company split (shinsetsu-bunkatsu) in which LAPIS established a new company, LAPIS Technology Co., Ltd. ("LAPIS Technology") and LAPIS Technology succeeded LAPIS Semiconductor's LSI business.

Therefore, all references to "LAPIS Semiconductor Co., Ltd.", "LAPIS Semiconductor" and/or "LAPIS" in this document shall be replaced with "LAPIS Technology Co., Ltd."

Furthermore, there are no changes to the documents relating to our products other than the company name, the company trademark, logo, etc.

Thank you for your understanding.

LAPIS Technology Co., Ltd.

October 1, 2020

# ML62Q1225 Reference Board User's Manual

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Issue Date: October 10, 2017



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**LAPIS Semiconductor Co.,Ltd.**

2-4-8 Shinyokohama, Kouhoku-ku,  
Yokohama 222-8575, Japan  
<http://www.lapis-semi.com/en/>

## Preface

This manual describes about the ML62Q1225 Reference Board : RB-D62Q1225MB16.

Refer to following documents when necessary.

- ML62Q1000 User's Manual  
Describes about the microcontroller ML62Q1000 series.
- EASE1000 User's Manual  
Describes about the On-chip emulator EASE1000.

## 1. Overview

### 1.1 Features

ML62Q1225 Reference Board is for learning how to use the ML62Q1225, on which adding external user components if necessary. Using ML62Q1225 Reference Board with LAPIS Semiconductor's on-chip emulator EASE1000 delivered with the software development environments, help user's software development and debugging and programming the Flash.

#### 1.1.1 ML62Q1225 Reference Board features

- The board delivered with ML62Q1225 16pin SSOP.
- The connector linked to ESE1000 is mounted.
- Through-holes for connecting the pins of LSI to external peripheral boards.
- The power supply is selectable, supplied from the on-chip emulator EASE1000 or CN1\_3pin / CN2\_2pin.
- LED is mounted (P20, P21, P22)

#### 1.1.2 ML62Q1225 Reference Board Hardware specifications

The hardware specification of ML62Q1225 Reference Board is indicated to Table 1.

Table.1 ML62Q1225 Reference Board Hardware specifications

Mounted LSI	U1 : ML62Q1225 16pin SSOP
Other Mounted components	PWR: Jumper for selecting the power supply input (3pin pin-header and short pin)
	J1: Jumper for selecting RESET_N pin (3pin pin-header and short pin)
	J2: Jumper for selecting P00/TEST0 pin (3pin pin-header and short pin)
	P20-P22: LEDs
	R1-R3: Resistors for LEDs by P20 to P22
	J3-J5: Jumper Chip for connecting LEDs
	CNE: Connector for EASE1000 (14pin connector)
	C1-C2: Capacitors for V <sub>DD</sub> and V <sub>DDL</sub>
	R4: Pull-up resistor for RESET_N
Pads (or/and) Through holes for mounting components	CN1-CN2: Connectors for user application system (25pin, 2.54mm pitch, φ 0.8mm)
Power check pin	VDD, VSS, UVDD: φ 0.8mm
Operating voltage	+1.6V to +5.5V
Board size	55.88 mm x 93.98 mm

See the schematic for more detail about connection of the mounted components.

### 1.2 ML62Q1225 Reference Board Outline Drawing

The Figure.1 show the ML62Q1225 Reference Board.

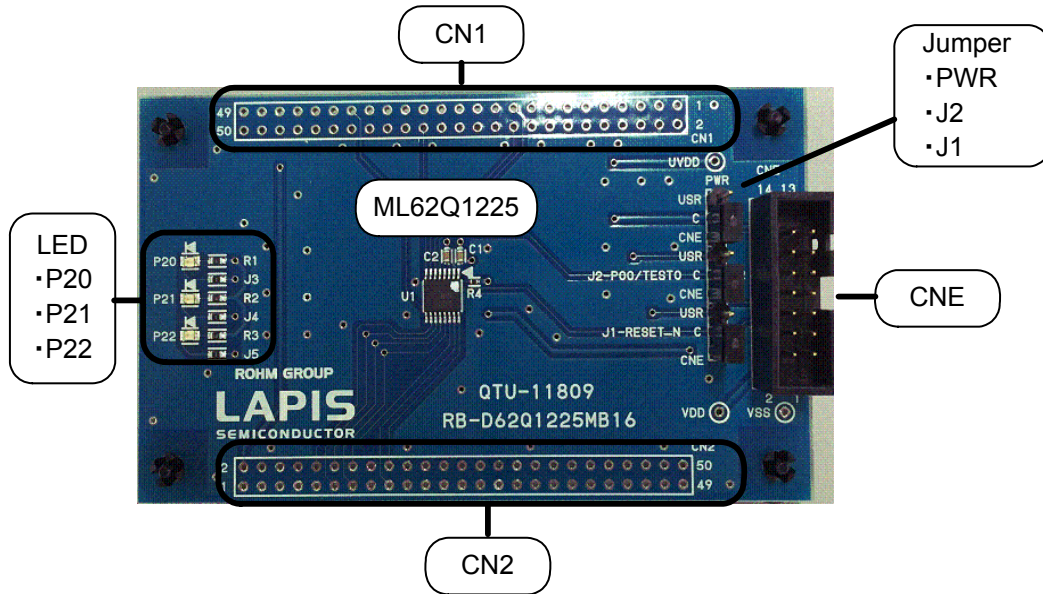


Fig.1 ML62Q1225 Reference Board Outline Drawing

## 2. Function of ML62Q1225 Reference Board

### 2.1 Power Circuit

V<sub>DD</sub> can select the input from 3.3VOUT of EASE1000 or CN1\_3pin / CN2\_2pin by PWR jumper.

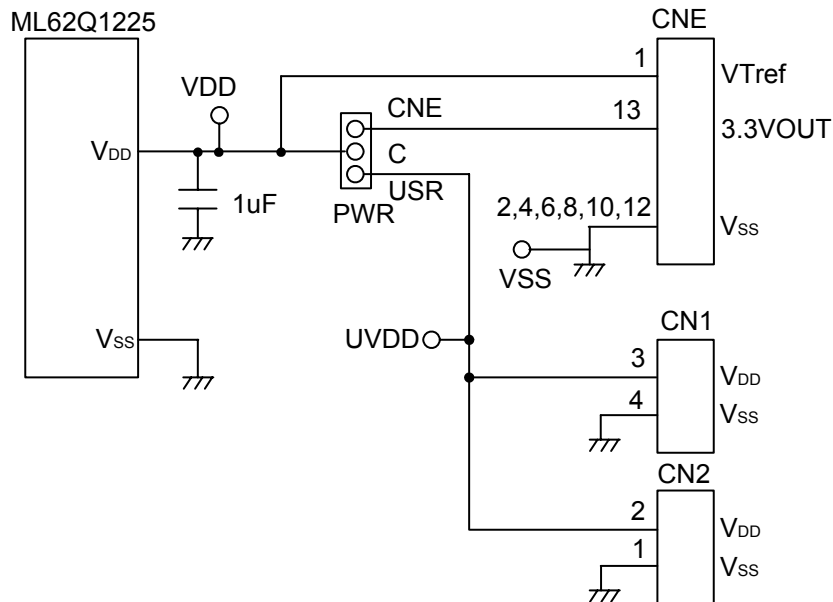


Fig.2 Power Circuit

[Note]

The power supply ON/OFF procedure in case of setting PWR jumper to the USB-side, and using EASE1000

- The procedure of power supply ON
  1. The USB cable of EASE1000 is connected.
  2. The power supply of user target system is turned on..
- The procedure of power supply OFF
  1. The power supply of user target system is turned off
  2. The .USB cable of EASE1000 is removed



## 2.2 Connector for EASE1000 (CNE)

EASE1000 can be used if J1 and J2 jumper are set to "CNE" .

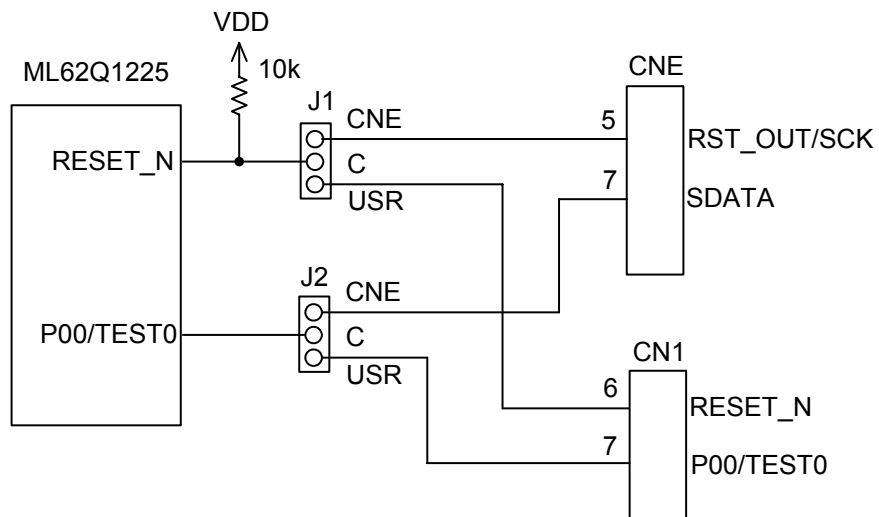


Fig.3 EASE1000 Interface

[Note]

P00/TEST0 pin:

P00/TEST0 pin of ML62Q1225 is initially set as the pulled-up input mode.

When using EASE1000 do not set it as an output mode by the application program, otherwise EASE1000 cannot communicate with the ML62Q1225.

### 2.3 LED (P20, P21, P22)

P20-P22 of the ML62q1225 are ports that can directly drive a LED. The Ports are connected to the LEDs through jumper-chip. Remove the jumper-chip when not using the LEDs.

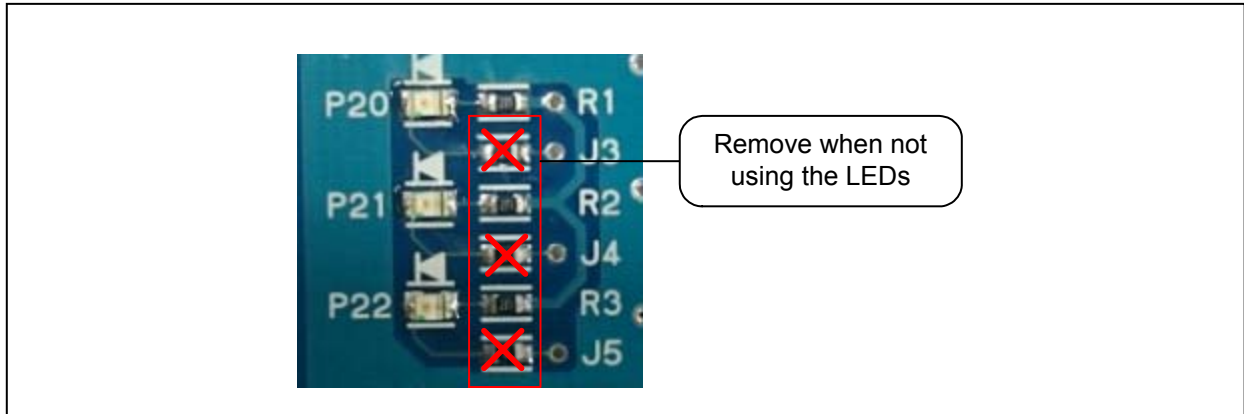


Fig.4 Jumper-chip removal of LEDs

### 3. User Interface

Table 2. show the pin list of the ML62Q1225 Reference Board user interface connector CN1 and CN2.

Table 2. ML62Q1225 Reference Board CN1/CN2

CN1	NAME	CN1	NAME	CN2	NAME	CN2	NAME
1	N.C.	26	N.C.	1	V <sub>SS</sub>	26	N.C.
2	N.C.	27	N.C.	2	V <sub>DD</sub>	27	N.C.
3	V <sub>DD</sub>	28	N.C.	3	N.C.	28	N.C.
4	V <sub>SS</sub>	29	N.C.	4	N.C.	29	N.C.
5	N.C.	30	P04	5	N.C.	30	N.C.
6	RESET_N	31	N.C.	6	N.C.	31	N.C.
7	P00/TEST0	32	N.C.	7	N.C.	32	N.C.
8	N.C.	33	N.C.	8	N.C.	33	N.C.
9	N.C.	34	N.C.	9	N.C.	34	N.C.
10	N.C.	35	N.C.	10	P17	35	N.C.
11	N.C.	36	N.C.	11	P20	36	N.C.
12	N.C.	37	P13	12	P21	37	N.C.
13	N.C.	38	N.C.	13	P22	38	N.C.
14	N.C.	39	N.C.	14	P23	39	N.C.
15	N.C.	40	N.C.	15	N.C.	40	N.C.
16	N.C.	41	N.C.	16	N.C.	41	N.C.
17	N.C.	42	N.C.	17	P26	42	N.C.
18	N.C.	43	N.C.	18	P27	43	N.C.
19	P02	44	N.C.	19	N.C.	44	N.C.
20	P03	45	N.C.	20	N.C.	45	N.C.
21	N.C.	46	N.C.	21	N.C.	46	N.C.
22	N.C.	35	N.C.	22	N.C.	35	N.C.
23	N.C.	48	N.C.	23	N.C.	48	N.C.
24	N.C.	49	N.C.	24	N.C.	49	N.C.
25	N.C.	50	N.C.	25	N.C.	50	N.C.

N.C. : Non-Connection

## 4. Precaution for use

- (1) The ML62Q1225 Reference Board is an unfinished product and intended for research and development and for expert use in the research and development facility only. The ML62Q1225 Reference Board is not intended for use for volume production or parts thereof.
- (2) Since the content specified herein is subject to change for improvement without notice, confirm the content is the latest when using the board.
- (3) See another documents ML62Q1000 series user's manual and EASE1000 user's manual when using the ML62Q1225 Reference Board.
- (4) Confirm the final electrical characteristics by using the mass production parts on your mass production boards.
- (5) LAPIS support replacing the board for an initial failure soon after the shipment, can not support repairing the board.
- (6) ML62Q1225 Reference Board have signal patterns on the underside, it might work in abnormal if using on conductive materials. Use it on insulating materials or having any preventable parts.

## 5. PCB specification, BOM and Schematic

### 5.1 ML62Q1225 Reference Board PCB specification

Figure 5. shows the Reference Board PCB dimensional outline drawing and layout of components.

PCB part number:  
RB-D62Q1225MB16

Dimension:  
55.88 mm x 93.98 mm

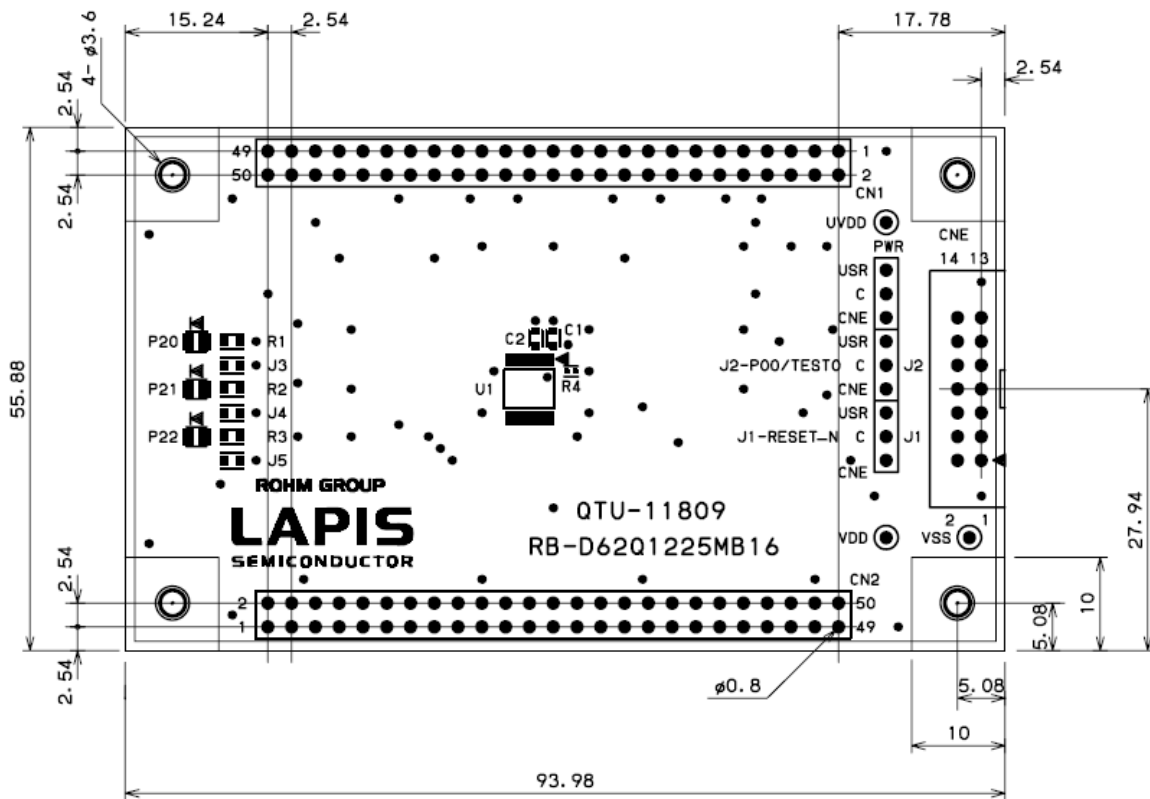


Fig.5 Reference Board PCB dimensional outline drawing and layout of components (Top view)

## 5.2 ML62Q1225 Reference Board BOM

Table 3. Reference Board BOM

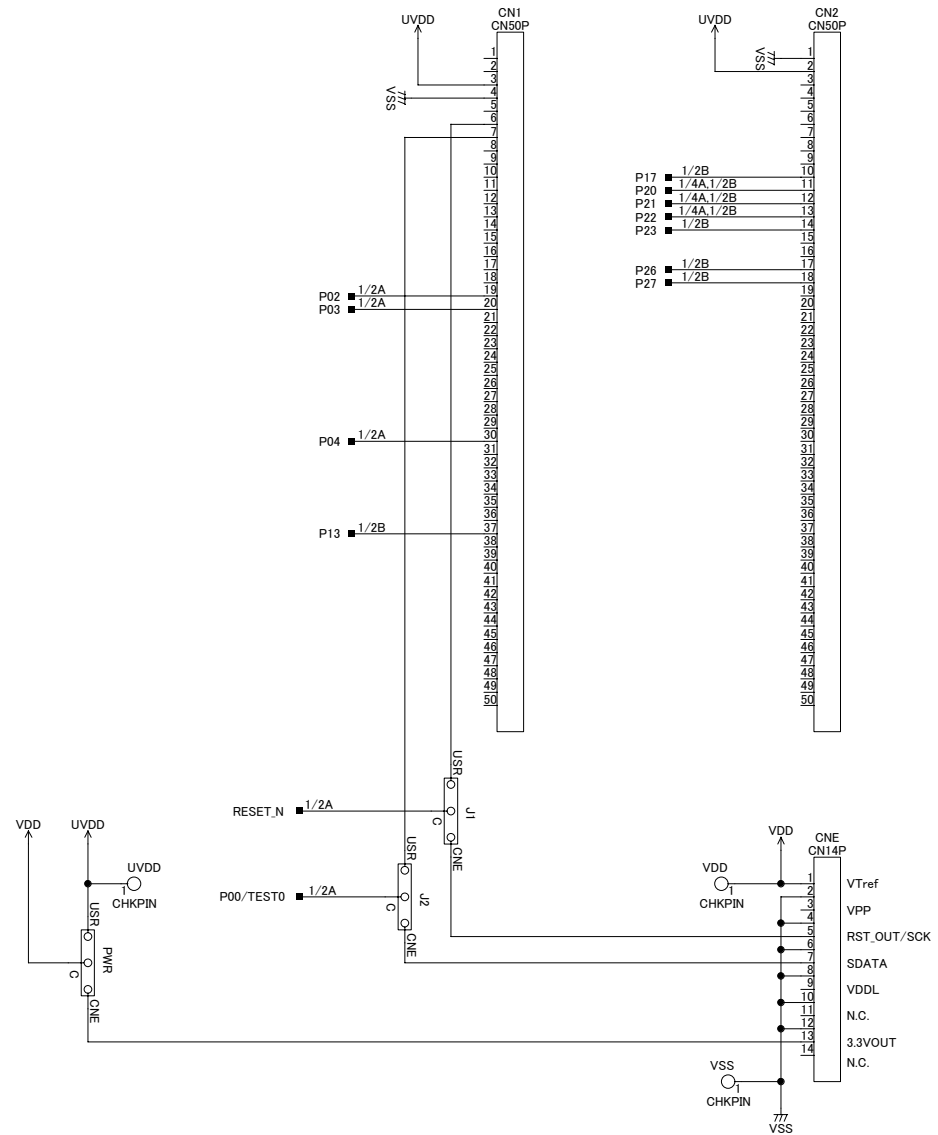
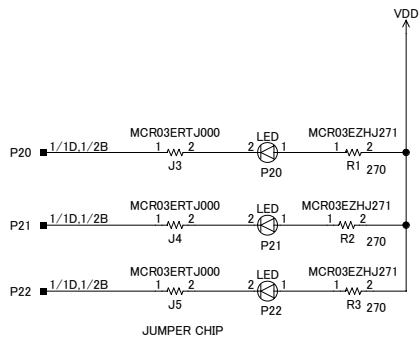
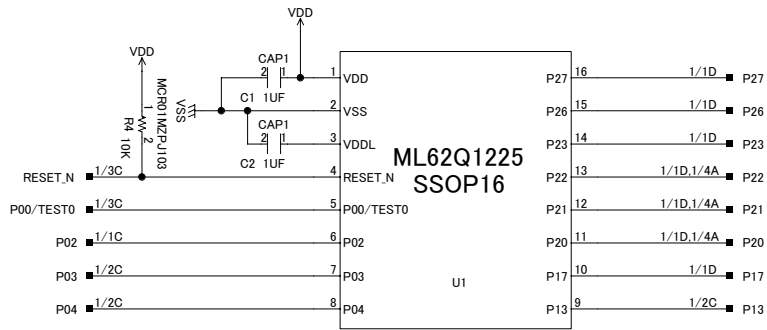
	Parts Number	Silk	Contents	Package Type	Qty.	Maker
1	QTU-11809	RB-D62Q1225MB16	PCB	-	1	LAPIS
2	ML62Q1225SSOP16	U1	ML62Q1225SSOP16	SSOP16	1	LAPIS
3	MCR03ERTJ000	J3, J4, J5	Jumper Chip	1608(1.6x0.8mm)	3	ROHM
4	SML-210PT	P20, P21, P22	ChipLED (Green)	2012(2.0x1.2mm)	3	ROHM
5	MCR03EZHZ271	R1, R2, R3	Chip Resistor 270Ω	1608(1.6x0.8mm)	3	ROHM
6	MCR01MZPJ103	R4	Chip Resistor 10kΩ	1005(1.0x0.5mm)	1	ROHM
7	GRM188R7YA105KA12D	C1, C2	Ceramic Capacitor 1uF/35V	1608(1.6x0.8mm)	2	MURATA
8	HIF3FC-14PA-2.54DSA	CNE	14pin Connector	14pin DIP	1	HIROSE
9	A2-3PA-2.54DSA	J1, J2, PWR	3pin Pin_Header	3pin DIP Straight	3	HIROSE
10	HIF3GA-2.54SP	-	Short pin	-	3	HIROSE
11	FF013-AR79	-	Rubber leg	-	4	KOYO FASTENER
12	P3555	-	Push rivet	-	4	KOYO FASTENER
13	A1-50PA-2.54DSA (Un-mounting)	CN1, CN2	50pin 2.54pitch φ0.8 mm	50pin Straight	2	HIROSE
14	Check Pin (Un-mounting)	VDD, VSS	φ0.8 mm	-	2	-

[Note]

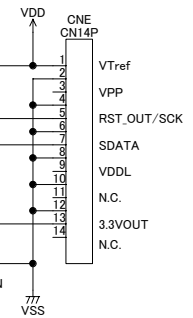
- The diameter of through hole of CN1 and CN2 is 0.8 mm.  
Using CN1 and CN2, the diameter of connector pin should use the connector below 0.8mm, such as 0.5mm.
- The parts may be changed into another parts with equivalent part special quality.

## 5.3 ML62Q1225 Reference Board Schematic

The next page shows the schematic of ML62Q1225 Reference Board



- P17 ■ 1/2B
- P20 ■ 1/4A, 1/2B
- P21 ■ 1/4A, 1/2B
- P22 ■ 1/4A, 1/2B
- P23 ■ 1/2B
- P26 ■ 1/2B
- P27 ■ 1/2B



LAPIS SEMICONDUCTOR CO.,LTD.		
TITLE	RB-D62Q1225MB16	
APPLICATION	ML62Q1225SSOP16RB	
DWG NO	QTS-11669	
DRAWN By	SHEET	9-14-2016_13:18 1/1 REV 1.00

## REVISION HISTORY

Document No.	Date	Page		Description
		Previous Edition	Current Edition	
FEBL62Q1225RB-01	November 8, 2016	-	-	First Edition
FEBL62Q1225RB-02	September 1, 2017	4	4	Fig1: Changed
		11	11	Table3: Corrected C1, C2
FEBL62Q1225RB-03	October 10,2017	11	11	Table3: Corrected C1, C2